PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY	

CONVEYING PARTY DATA

Name	Execution Date
Enterprise Partners V, L.P.	06/10/2011
Enterprise Partners VI, L.P.	06/10/2011
Richard S. Post	06/10/2011

RECEIVING PARTY DATA

Name:	Nexx Systems, Inc., a Delaware Corporation	
Street Address:	900 Middlesex Turnpike	
Internal Address:	Building 6	
City:	Billerica	
State/Country:	MASSACHUSETTS	
Postal Code:	01821	

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	6251250

CORRESPONDENCE DATA

Fax Number: (313)496-8454 Phone: 3134967562

Email: spano@millercanfield.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US

Mail.

Correspondent Name: Kristen I. Spano

Address Line 1: 150 West Jefferson Avenue

Address Line 2: Suite 2500

Address Line 4: Detroit, MICHIGAN 48226

ATTORNEY DOCKET NUMBER:	125055-810
NAME OF SUBMITTER:	Kristen I. Spano

Total Attachments: 3

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PATENT REEL: 027184 FRAME: 0611 ~H &40 00

REASSIGNMENT AND RELEASE OF SECURITY INTEREST

This Reassignment and Release of Security Interest is made as of June 10, 2011 by the following (collectively as "Secured Party"):

Enterprise Partners VI, L.P., as collateral agent Enterprise Partners VI, L.P., Enterprise Partners V, L.P., Richard S. Post.

in favor of **Nexx Systems**, **Inc.**, a Delaware corporation ("<u>Grantor</u>"), with its principal place of business at 900 Middlesex Turnpike, Building 6, Billerica, Massachusetts 01821.

Grantor has collaterally assigned certain interests in the patents described on Exhibit A ("<u>Patents</u>") to Secured Party under the Loan and Security Agreement dated as of October 31, 2007, and recorded with the United States Patent and Trademark Office as set forth on Exhibit A.

Secured Party hereby releases its security interest in the Patents and reassigns to Grantor, without warranty or recourse, all interest of Secured Party in the Patents.

01/11
By: / 4 / 1
Name: CARL EIBL
Its: MANAGING PARTHER
Enterprise Partners VI, L.P.
By: A E.
Its: / Nonsoine Partner
Enterprise Partners V, L.P.
By: / al /2-il/
Name: Carl E.61
Its: MANSOING PARTNER
Signature:
Name: Richard S. Post

Enterprise Partners VI, L.P., as collateral agent

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Enterprise Partners VI, L.P., as collateral agent

EXHIBIT A Patents

Patent / Application Number	Recordation Date	Reel/Frame Number	Description
6,217,272	11/04/04	015328/0752	In-Line sputter deposition system
	11/05/04	015334/0079	
6,251,250	11/05/04	015334/0071	Method of and apparatus for controlling fluid flow and electric fields involved in the electroplating of substantially flat workpieces and the like and more generally controlling fluid flow in the processing of other workpiece surfaces as well
6,328,858	11/04/04	015328/0752	Multi-layer sputter deposition appartus
<u>.</u>	11/05/04	015334/0079	
6,396,024	11/04/04 11/05/04	015328/0752 015334/0079	Permanent magnet ECR plasma source with integrated multipolar magnetic confinement
6,530,733	11/04/04 11/05/04	015328/0752 015334/0079	Substrate processing pallet and related substrate processing method and machine
6,682,288	11/04/04	015328/0752	Substrate processing pallet and related substrate processing method and machine
	11/05/04	015334/0079	•
6,821,912	11/04/04	015328/0752 015334/0079	Substrate processing pallet and related substrate processing method and machine
7,100,954	11/04/04	015328/0752	Ultra-thin wafer handling system

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19,103,445.1\125055-00810

RECORDED: 11/07/2011